# Raise3D Pro3 Series Technical Specifications

*Raise3D Pro3 Series professional dual extruder 3D printers meet the needs of both production and multi-sized rapid prototyping, with high precision, large build size and round-the-clock stable operation. It is easy to use, and affordable for both office and manufacturing use.*

| Printer | Raise3D Pro3 | | Raise3D Pro3 Plus | |
|---|---|---|---|---|
| **Build Volume** (W × D × H) | Single Extruder Print | Dual Extruder Print | Single Extruder Print | Dual Extruder Print |
| | 300 × 300 × 300 mm (11.8 × 11.8 × 11.8 inch) | 255 × 300 × 300 mm (10 × 11.8 × 11.8 inch) | 300 × 300 × 605 mm (11.8 × 11.8 × 23.8 inch) | 255 × 300 × 605 mm (10 × 11.8 × 23.8 inch) |
| **Machine Size** (W × D × H) | 620 × 626 × 760 mm (24.4 × 24.6 × 29.9 inch) | | 620 × 626 × 1105 mm (24.4 × 24.6 × 43.5 inch) | |

| Weight | Net Weight | Gross Weight (Carton Only) | Gross Weight (Carton with Pallet) | Net Weight | Gross Weight (Carton Only) | Gross Weight (Carton with Pallet) |
|---|---|---|---|---|---|---|
| | 56.2 kg (123.9 lbs) | 67 kg (147.8 lbs) | 74.5 kg (164.3 lbs) | 66.6 kg (146.9 lbs) | 83.3 kg (183.7 lbs) | 90.8 kg (200.2 lbs) |

| Electrical | | |
|---|---|---|
| | Power Supply Input | 100-240 V AC, 50/ 60 Hz 230 V @ 3.3 A |
| | Power Supply Output | 24 V DC, 600 W |

| General | | |
|---|---|---|
| | Print Technology | Fused Filament Fabrication (FFF) |
| | Print Head System | Dual-head with Electronic Lifting System |
| | Filament Diameter | 1.75 mm |
| | XYZ Step Size | 0.78125, 0.78125, 0.078125 micron |
| | Print Head Travel Speed | 15-350 mm/s |
| | Build Plate | Flexible Steel Plate with BuildTak |
| | Max Build Plate Temperature | 120℃ |
| | Heated Bed Material | Silicone |
| | Build Plate Leveling | Mesh-leveling with Flatness Detection |
| | Filament Run-out Sensor | Available |
| | Layer Height | The Pro3 Series is compatible with 0.2, 0.4, 0.6, 0.8 and 1.0 mm nozzles, and the layer height can vary between 0.05-0.6 mm. To achieve stable print results, when using 0.4 mm nozzles, we recommend using a layer height between 0.1-0.3 mm. |
| | Nozzle Diameter | 0.4 mm (Default), 0.2/ 0.6/ 0.8/ 1.0 mm (Available) |
| | Max Nozzle Temperature | 300℃ |
| | Connectivity | Wi-Fi, LAN, USB port, Live Camera |
| | Noise Emission (Acoustic) | < 55 dB (A) When Building |
| | Operating Ambient Temperature | 15-30℃, 10-90% RH, non-condensing |
| | Storage Temperature | -25℃ to +55℃, 10-90% RH, non-condensing |
| | Filter | HEPA Filter with Activated Charcoal |
| | EVE Smart Assistant | Available |

| Material | | |
|---|---|---|
| | Material Type | PLA/ ABS/ ASA/ PETG/ PC/ PETG ESD/ TPU 95A/ PVA+ |
| | Third Party Material | Supported by Raise3D OFP (Open Filament Program)* |

| Software | | |
|---|---|---|
| | Slicing Software | ideaMaker |
| | Supported File Types | STL/ OBJ/ 3MF/ OLTP |
| | Supported OS | Windows/ macOS/ Linux |
| | Machine Code Type | GCODE |

| Printer Controller | | |
|---|---|---|
| | User Interface | 7-inch Touch Screen |
| | Network | Wi-Fi, Ethernet |
| | Power Loss Recovery | Available |
| | Screen Resolution | 1024 × 600 |
| | Motion Controller | Atmel ARM Cortex-M4 120 MHz FPU |
| | Logic Controller | NXP ARM Cortex-A9 Quad 1 GHz |
| | Memory | 1 GB |
| | Onboard Flash | 16 GB |
| | OS | Embedded Linux |
| | Ports | USB 2.0 × 2, Ethernet × 1 |

*For detailed information and slicing profiles of the materials supported by Raise3D OFP, please visit *https://www.ideamaker.io/.*

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